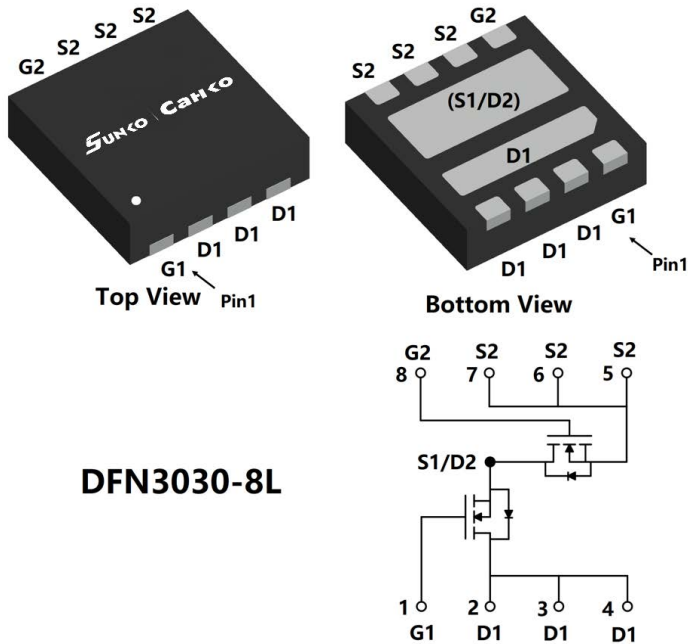


N-Channel and N-Channel Complementary MOSFET



Product Summary

NMOS(Die1)

• V_{DS}	30V
• I_D	30A
• $R_{DS(ON)}$ (at $V_{GS}=10V$)	<10mΩ
• $R_{DS(ON)}$ (at $V_{GS}=4.5V$)	<19.5mΩ

NMOS(Die2)

• V_{DS}	30V
• I_D	40A
• $R_{DS(ON)}$ (at $V_{GS}=10V$)	<6.5mΩ
• $R_{DS(ON)}$ (at $V_{GS}=4.5V$)	<15mΩ

General Description

- Dual Asymmetric N-Channel
- High Current Capability
- Low Gate Charge
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC/DC Converters in Computing, Servers
- Isolated DC/DC Converters in Telecom and Industrial

■ Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	NMOS(Die1)	NMOS(Die2)	Unit
Drain-source Voltage		V_{DS}	30	30	V
Gate-source Voltage		V_{GS}	±20	±20	V
Drain Current	$T_A=25^{\circ}C$	I_D	9	11	A
	$T_A=100^{\circ}C$		5	7	
	$T_C=25^{\circ}C$		30	40	
	$T_C=100^{\circ}C$		19	25	
Pulsed Drain Current ^A		I_{DM}	120	160	A
Avalanche energy ^B		EAS	42.2	60	mJ
Total Power Dissipation ^C	$T_A=25^{\circ}C$	P_D	1.56	1.66	W
	$T_A=100^{\circ}C$		0.62	0.66	
	$T_C=25^{\circ}C$		17.3	20.8	
	$T_C=100^{\circ}C$		6.9	8.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	-55~+150	°C

■ Thermal resistance

Parameter		Symbol	NMOS(Die1)		NMOS(Die2)		Units
			Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient ^D	Steady-State	$R_{\theta JA}$	67	80	62	75	°C/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	6	7.2	5	6	

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCQD3622A	F1	QD3622A	3000	30000	120000	13" reel

SCQD3622A

■ NMOS(Die1) Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
		V _{DS} =30V, V _{GS} =0V, T _J =150℃	-	-	100	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.1	1.5	2.2	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =13A	-	7.5	10	mΩ
		V _{GS} =4.5V, I _D =10A	-	14	19.5	
Diode Forward Voltage	V _{SD}	I _S =10A, V _{GS} =0V	-	-	1.2	V
Gate resistance	R _G	f=1MHz	-	3	-	Ω
Maximum Body-Diode Continuous Current	I _S		-	-	30	A
Dynamic Parameters						
Input Capacitance	C _{iSS}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	1020	-	pF
Output Capacitance	C _{oSS}		-	140	-	
Reverse Transfer Capacitance	C _{rSS}		-	125	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =13A	-	20.7	-	nC
Gate-Source Charge	Q _{gs}		-	3.8	-	
Gate-Drain Charge	Q _{gd}		-	5.3	-	
Reverse Recovery Charge	Q _{rr}	I _F =13A, di/dt=100A/us	-	161	-	nC
Reverse Recovery Time	t _{rr}		-	136	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =15V, I _D =13A R _{GEN} =2.2Ω	-	8.2	-	ns
Turn-on Rise Time	t _r		-	53.9	-	
Turn-off Delay Time	t _{D(off)}		-	18.4	-	
Turn-off fall Time	t _f		-	2.9	-	

SCQD3622A

■ NMOS(Die2) Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
		V _{DS} =30V, V _{GS} =0V, T _j =150℃	-	-	100	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.1	1.5	2.2	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =15A	-	5	6.5	mΩ
		V _{GS} =4.5V, I _D =10A	-	11	15	
Diode Forward Voltage	V _{SD}	I _S =10A, V _{GS} =0V	-	-	1.2	V
Gate resistance	R _G	f=1MHz	-	3	-	Ω
Maximum Body-Diode Continuous Current	I _S		-	-	40	A
Dynamic Parameters						
Input Capacitance	C _{iSS}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	1320	-	pF
Output Capacitance	C _{oSS}		-	185	-	
Reverse Transfer Capacitance	C _{rSS}		-	170	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =15A	-	27	-	nC
Gate-Source Charge	Q _{gs}		-	5	-	
Gate-Drain Charge	Q _{gd}		-	7	-	
Reverse Recovery Charge	Q _{rr}	I _F =15A, di/dt=100A/us	-	157	-	nC
Reverse Recovery Time	t _{rr}		-	130	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =15V, ID=15A R _{GEN} =2.2Ω	-	10.8	-	ns
Turn-on Rise Time	t _r		-	64.8	-	
Turn-off Delay Time	t _{D(off)}		-	22.5	-	
Turn-off fall Time	t _f		-	3.7	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. NMOS(Die1): T_J=25°C, V_G=10V, R_G=25Ω, L=0.5mH, I_{AS}=13A.

NMOS(Die2): T_J=25°C, V_G=10V, R_G=25Ω, L=0.5mH, I_{AS}=15.5A.

C. P_d is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.

D. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with T_A =25°C.

The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

■ NMOS(Die1) Typical Electrical and Thermal Characteristics Diagrams

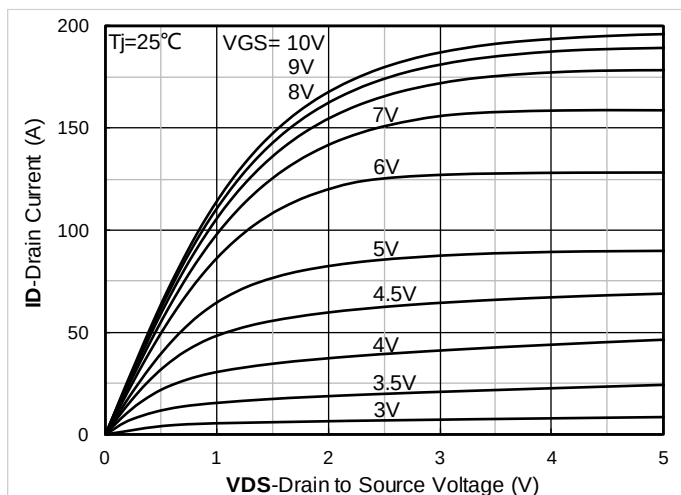


Figure 1. Output Characteristics

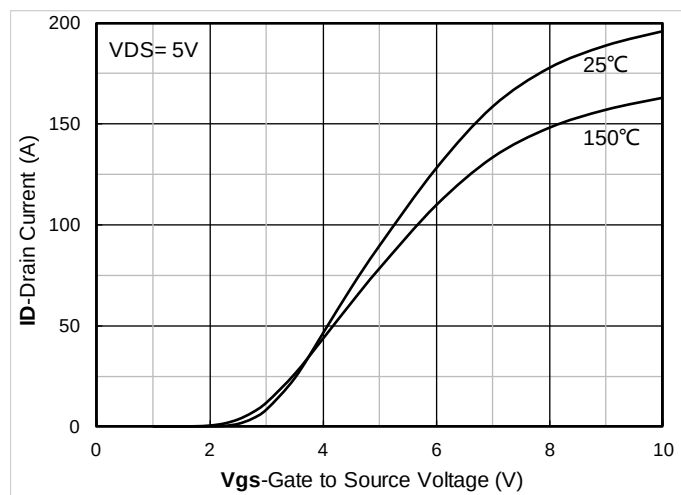


Figure 2. Transfer Characteristics

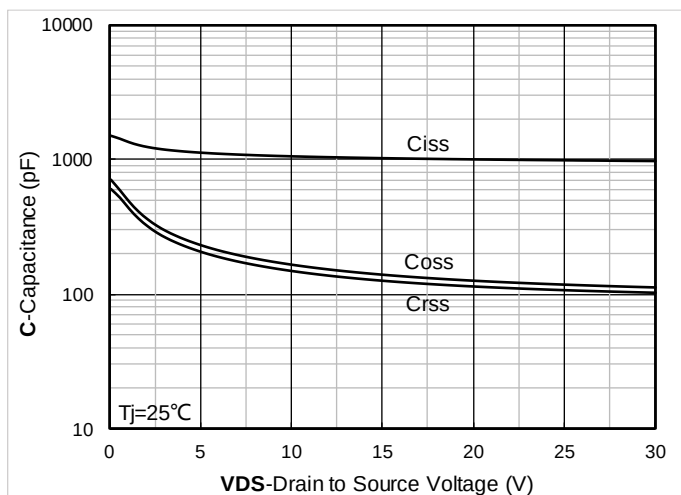


Figure 3. Capacitance Characteristics

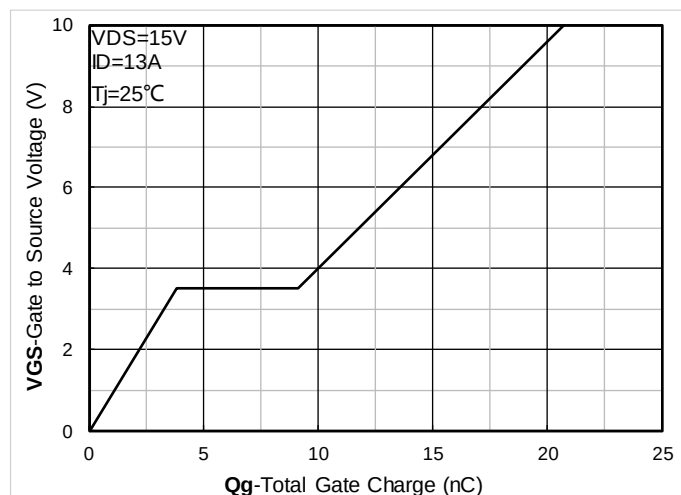


Figure 4. Gate Charge

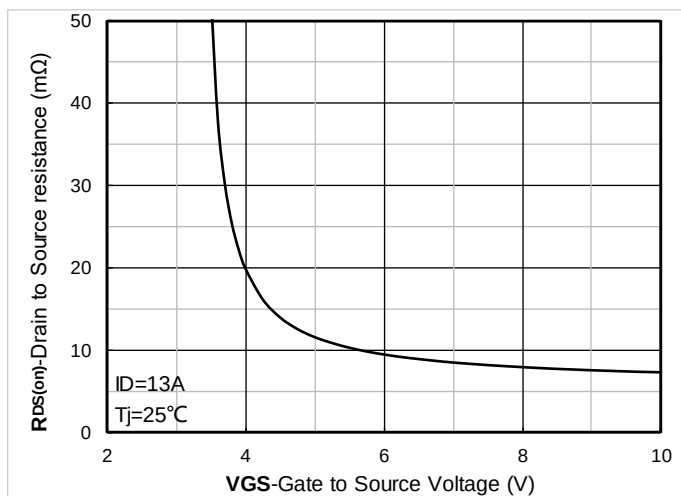


Figure 5. On-Resistance vs Gate to Source Voltage

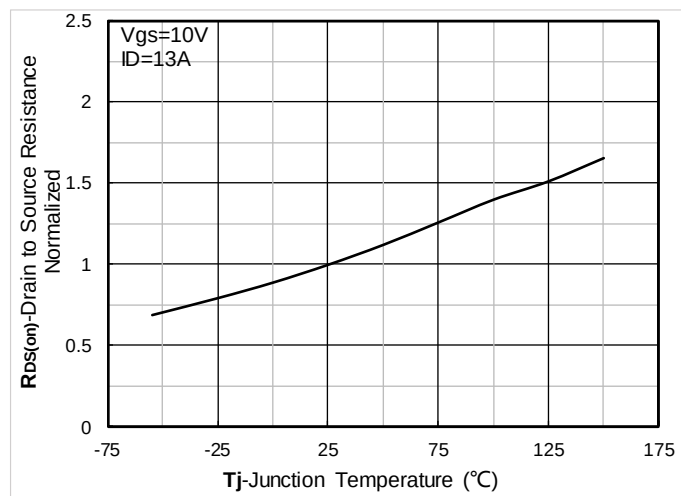


Figure 6. Normalized On-Resistance

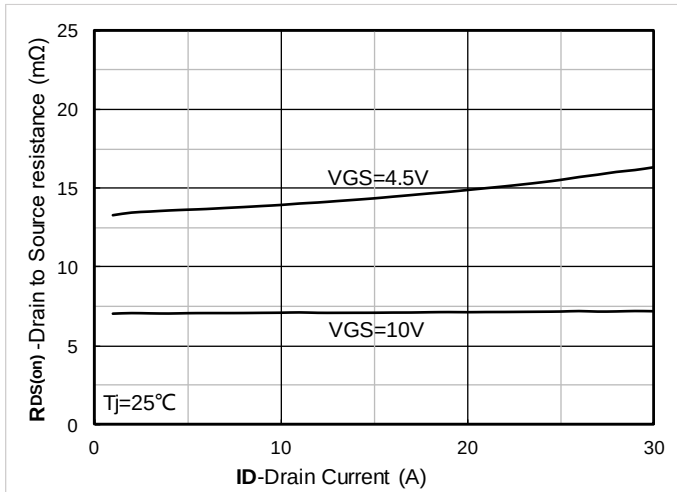


Figure 7. $R_{DS(on)}$ VS Drain Current

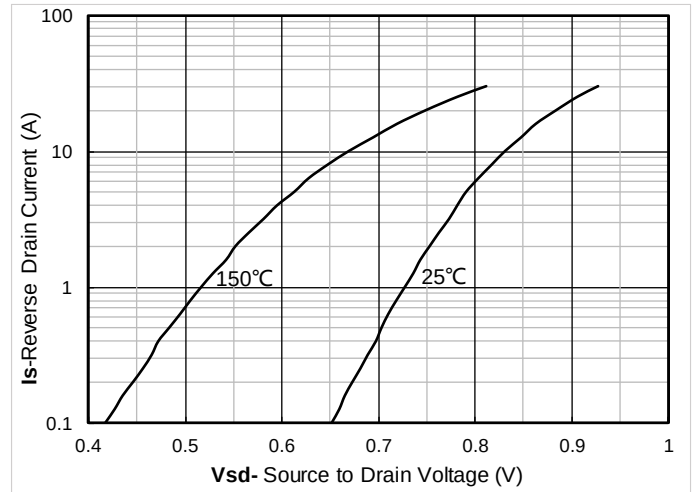


Figure 8. Forward characteristics of reverse diode

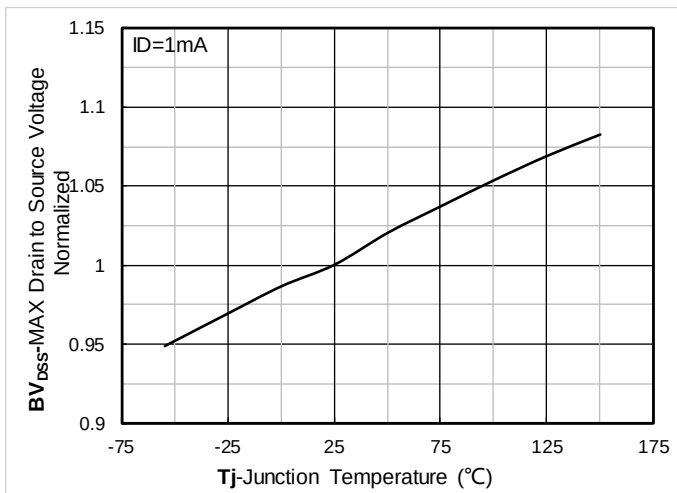


Figure 9. Normalized breakdown voltage

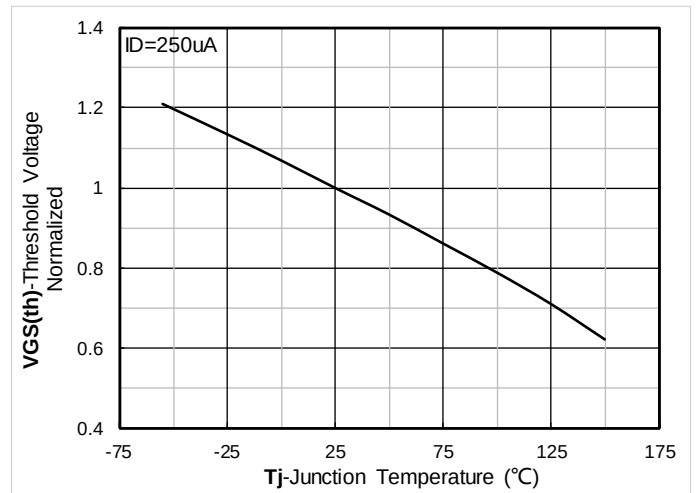


Figure 10. Normalized Threshold voltage

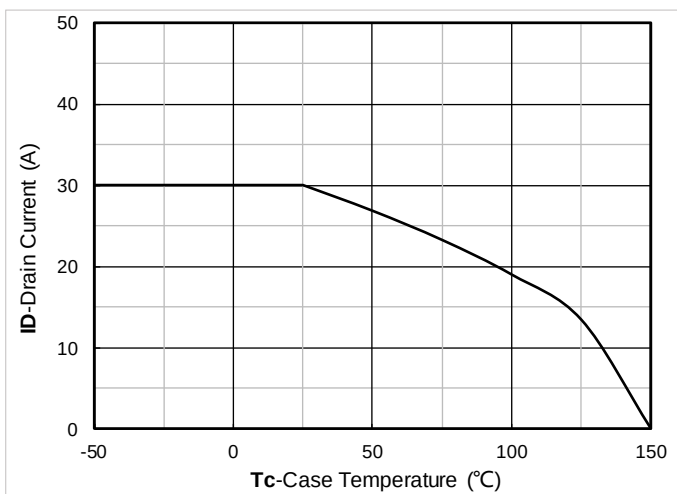


Figure 11. Current dissipation

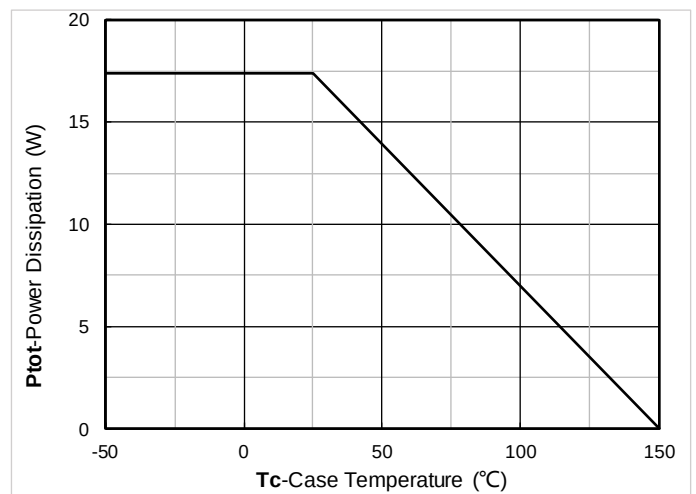


Figure 12. Power dissipation

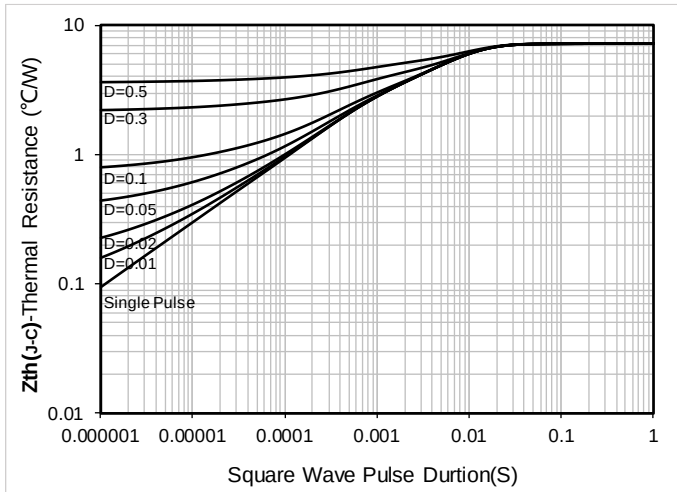


Figure 13. Maximum Transient Thermal Impedance

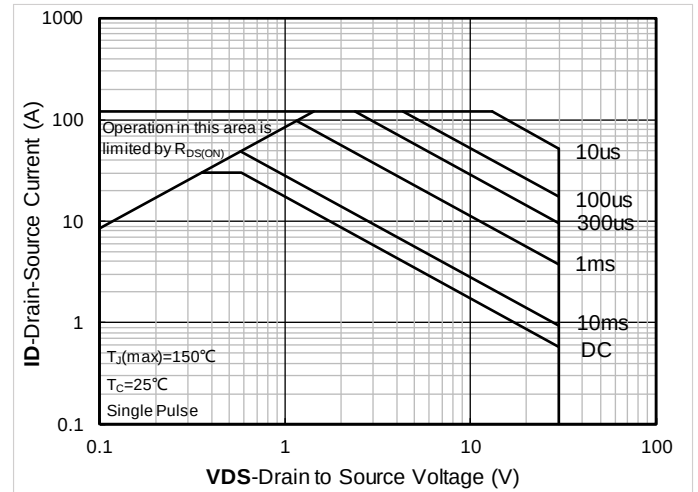


Figure 14. Safe Operation Area

■ NMOS(Die2) Typical Electrical and Thermal Characteristics Diagrams

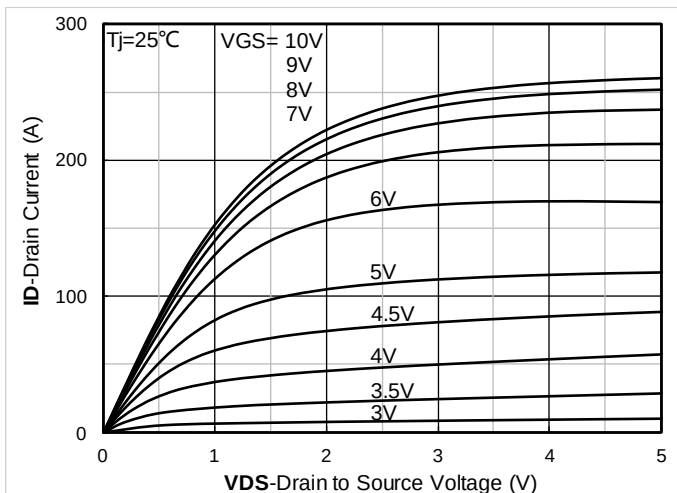


Figure 1. Output Characteristics

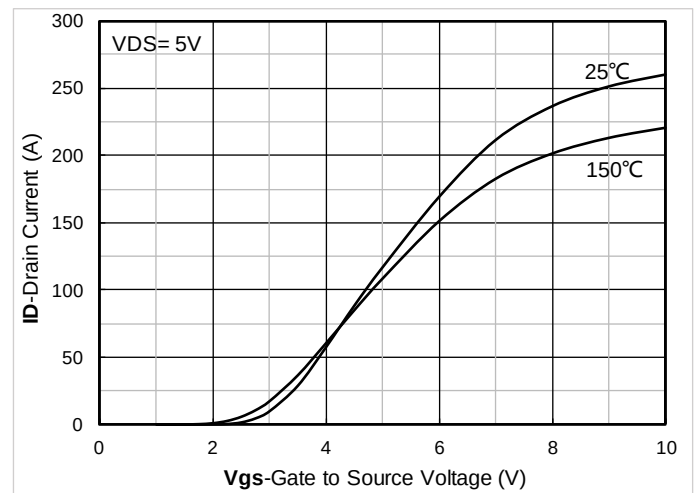


Figure 2. Transfer Characteristics

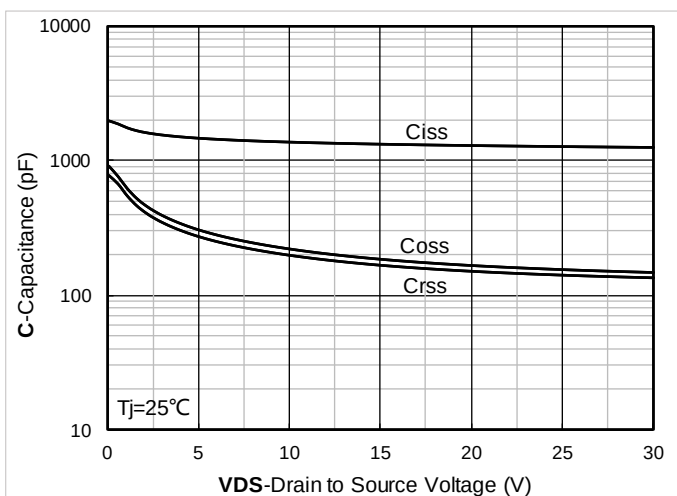


Figure 3. Capacitance Characteristics

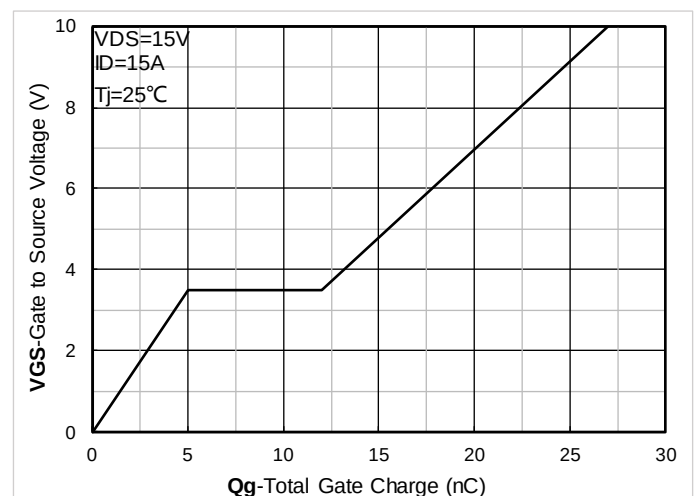


Figure 4. Gate Charge

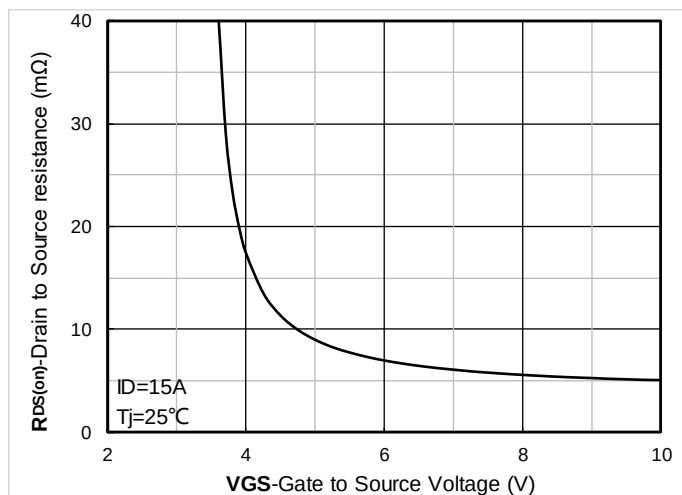


Figure 5. On-Resistance vs Gate to Source Voltage

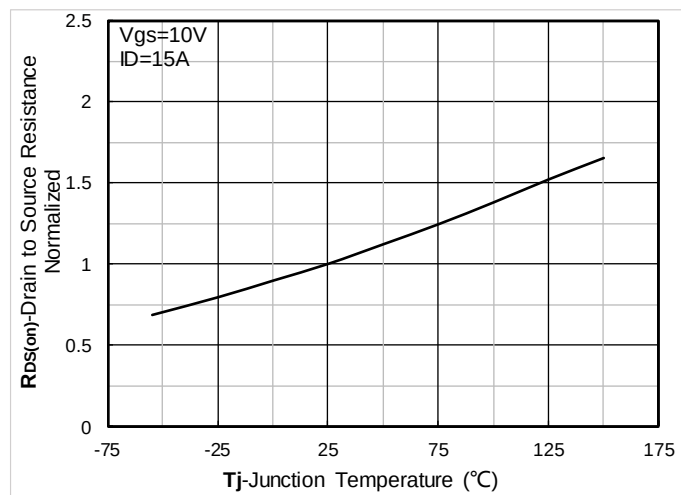


Figure 6. Normalized On-Resistance

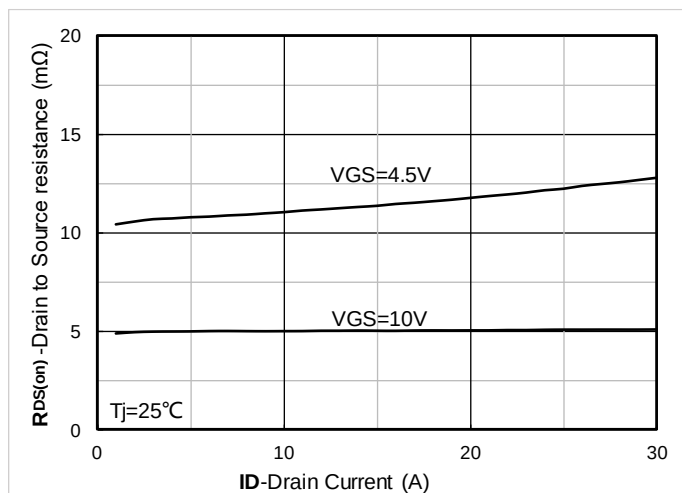


Figure 7. $R_{DS(on)}$ VS Drain Current

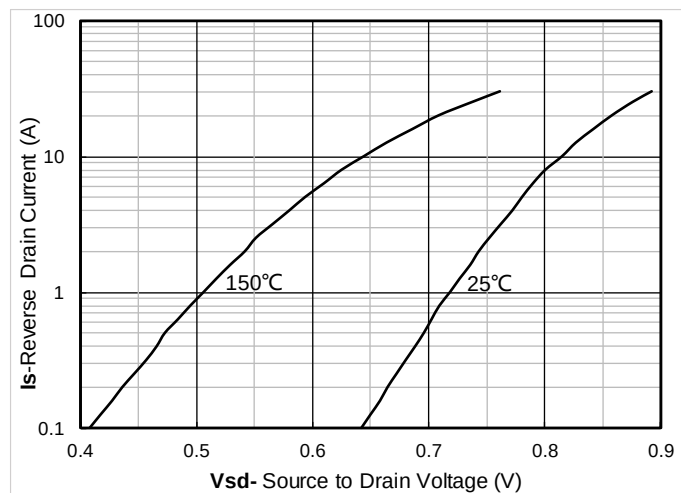


Figure 8. Forward characteristics of reverse diode

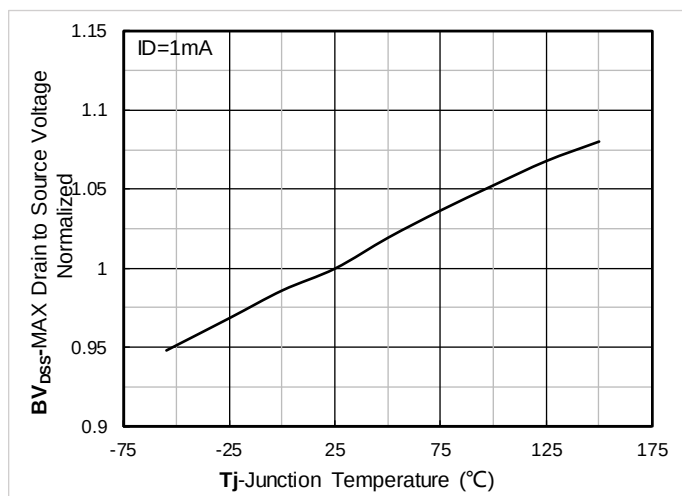


Figure 9. Normalized breakdown voltage

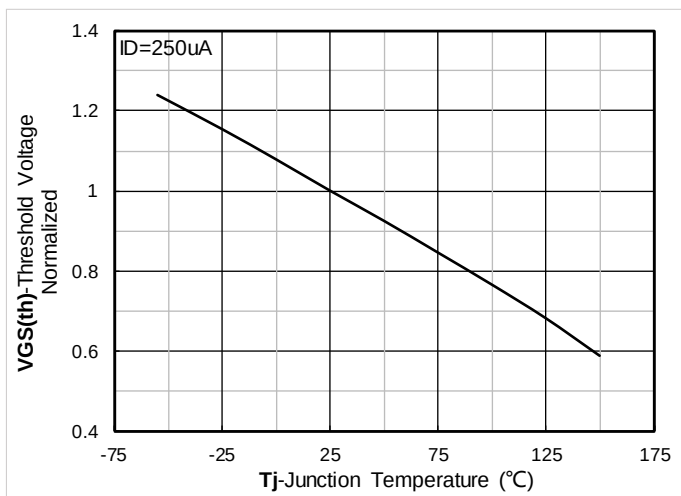


Figure 10. Normalized Threshold voltage

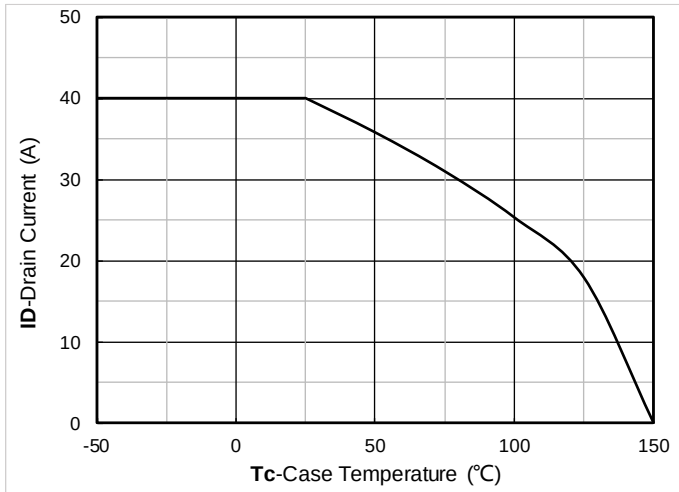


Figure 11. Current dissipation

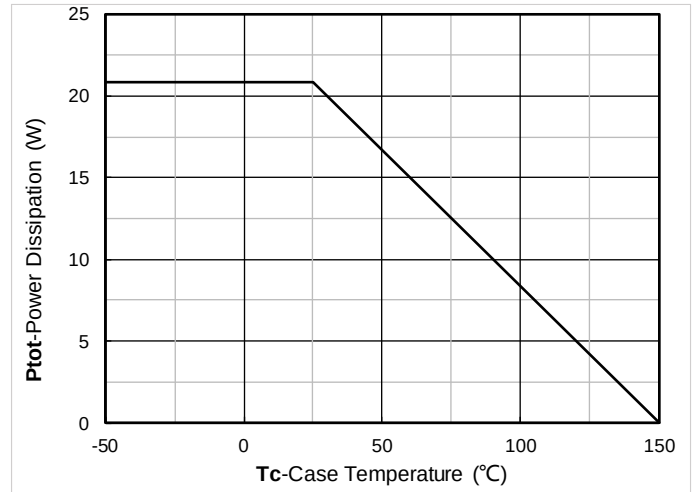


Figure 12. Power dissipation

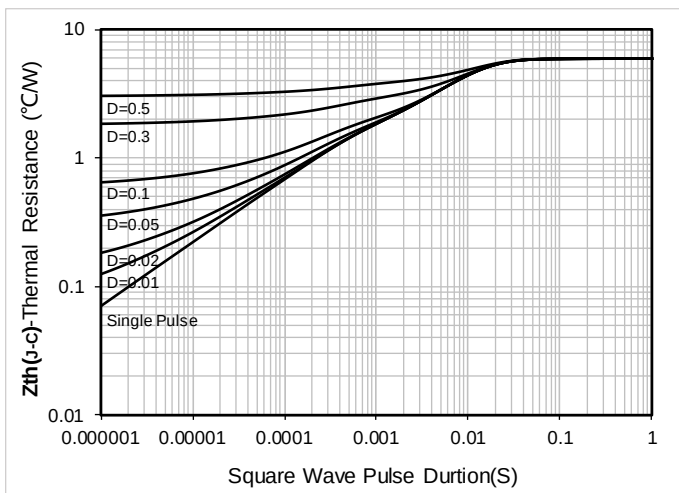


Figure 13. Maximum Transient Thermal Impedance

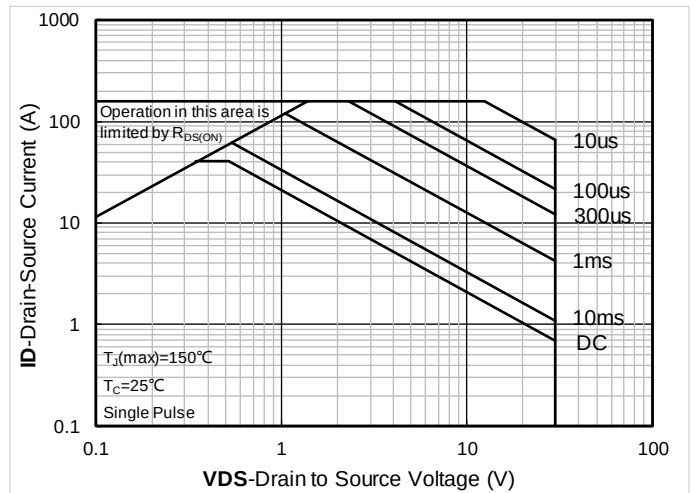
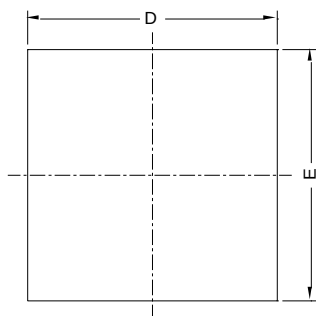
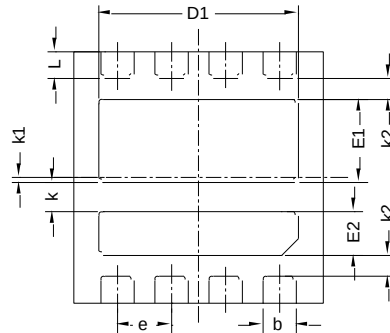


Figure 14. Safe Operation Area

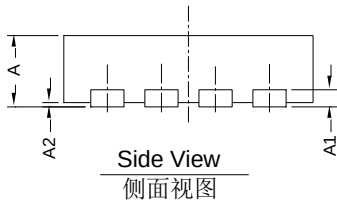
■ DFN3030-8L Package information



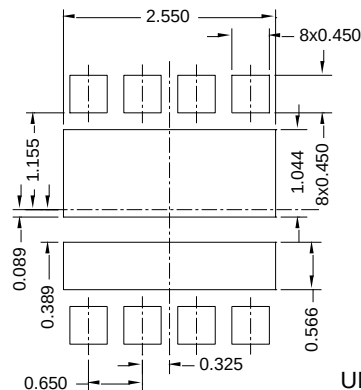
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

UNIT:mm

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	2.90	3.00	3.10
E	2.90	3.00	3.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	2.30	2.40	2.50
E1	0.89	0.99	1.09
E2	0.42	0.52	0.62
L	0.22	0.32	0.42
k	0.35 BSC		
k1	0.06 BSC		
k2	0.25 BSC		
b	0.30	0.40	0.50
e	0.65 BSC		

Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.10mm.
- 3.The pad layout is for reference purposes only.

Disclaimer

The information presented in this document is for reference only. Shanghai Sunco Electronics Co., Ltd reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices). Russiansunco or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.russiansunco.co> or consult your nearest Russiansunco's sales office for further assistance.